



Selective Soldering System HSS 3235

Selective Soldering with Short Cycle Times

- **Selective soldering of leaded devices and connectors after reflow.**
- **Simultaneous processing assures short cycle times (15-20 sec. depending on application).**
- **High process reliability because of large solder volume and a closed loop wave height control.**
- **Flexible system concept.**
- **Bare board handling or processing of carriers possible.**
- **Ideally suited for inline processes.**

Area of Application: Selective Soldering with Short Cycle Times

The HSS 3235 (High-volume **S**elective **S**ystem) is ideal, as a supplement to reflow processes, to solder leaded components or connectors. This applies specifically when short cycle times are required for large volume production.

Both, bare boards as well as carriers can be processed and of course the HSS 3235 may be integrated into a fully automated production line.

The Individual Modules and Process Steps:

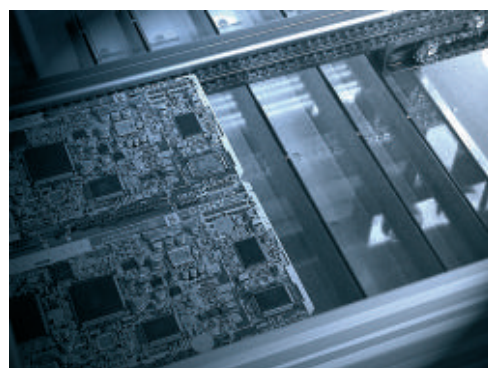
Depending on the size of PCB to be soldered, the HSS 3235 feeds one or more assemblies into the different machine areas: fluxer, preheating or soldering area. In each case, all joints will be fluxed, preheated or soldered in parallel and at the same time which guarantees shortest cycle times.

Additionally, the HSS 3235 is equipped with a segmented conveyor system, allowing individual profile settings.

Let's first have a look on the first process step: fluxing. The cycle time in this area is independent from the number of solder joints, as all joints will be fluxed simultaneously. Depending on your application, a stamp fluxing system or a coordinate spray fluxer may be integrated. The product-specific tools which are used for the stamp fluxer of course are quickly exchangeable. Optionally, a programmable coordinate fluxing unit can be installed to avoid change-over times. Micro drop jet nozzles guarantee minimum flux residues.



The preheating zone consists of heating modules with IR emitters and may be supplemented with a convection heating module. This guarantees an efficient and very homogeneous heat transfer.



In the soldering area SEHO's HSS 3235 uses the dip soldering process with high precision solder nozzle arrangements, which of course are also quickly exchangeable.

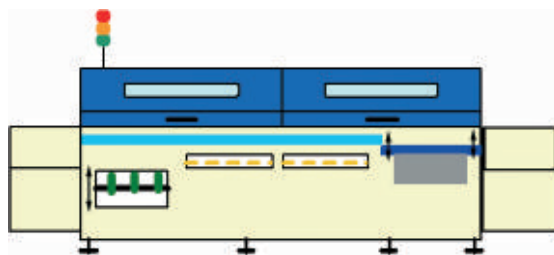
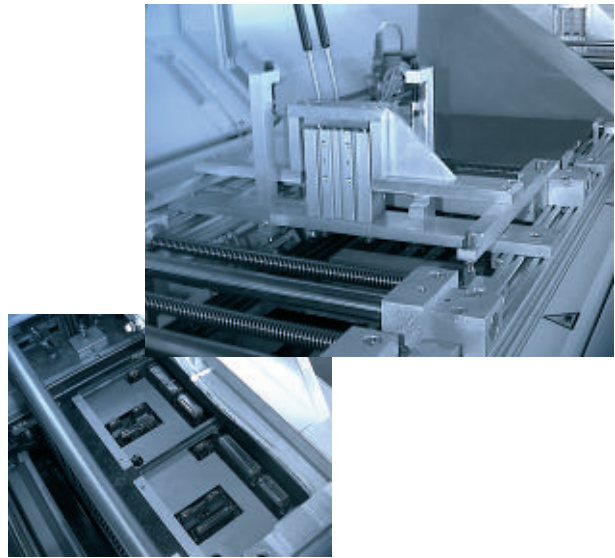
The soldering area incorporates a number of technical innovations, which contribute to

- excellent wetting of your solder joints
- perfect peel-off even at fine-pitch connectors
- reliable filling of through-holes even in thick PCBs.

Furthermore, the HSS 3235 offers a wave height control and regulating system as well as a large solder volume. Together, they assure a stable wave crest position.

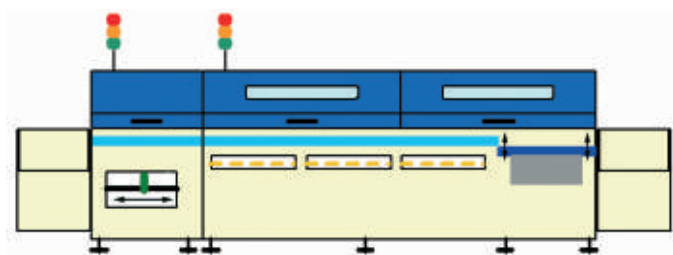
With an efficient nitrogen inertion system on the wave and the solder bath, SEHO ensures low maintenance requirements and a soldering process meeting highest quality demands.

Of course, the HSS 3235 is ideally suited for the processing of leadfree solder alloys.



standard configuration with

- stamp fluxer
- 2 IR preheat zones
- soldering module



extended configuration with

- coordinate fluxing system
- 3 preheat zones (IR and/or convection)
- soldering module

Equipment Features

Robust stainless steel frame	●
Conveyor	
Pin-and-chain conveyor	●
Conveyor width	350 mm
Conveyor inlet and outlet module (driven)	○
Loading and unloading support	○
Return conveyor in the bottom frame of the machine	○
Flux System	
Stamp fluxer	●
Coordinate fluxing system	○
Preheating System	
IR emitters (2 modules)	●
Convection module	○
Soldering Module	
Max. soldering area of 240 x 300 mm	●
Multiple nozzle tool for dip soldering processes (product-specific)	○
Nitrogen application unit for the wave area	●
Wave height control system	○
Automatic solder pot level control	○
Automatic solder wire feeder	○
Control System	
LCD display	●

Further options upon request.

● Standard ○ Option